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PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Pai-Hung Pan

Serial No.: 09/944,506

Filed: August 30, 2001

For: TECHNIQUE FOR FORMING  
SHALLOW TRENCH ISOLATION  
STRUCTURE WITHOUT CORNER  
EXPOSURE AND RESULTING  
STRUCTURE

Confirmation No.: 4348

Examiner: Unknown


Group Art Unit: 2823

Attorney Docket No.: 2919.5US (96-499.2)

CERTIFICATE OF MAILING

I hereby certify that this correspondence along with any attachments referred to or identified as being attached or enclosed is being deposited with the United States Postal Service as First Class Mail on the date of deposit shown below with sufficient postage and in an envelope addressed to the Commissioner for Patents, Washington, D.C. 20231.

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SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

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Sir:

In compliance with the duty to disclose information material to patentability pursuant to 37 C.F.R. § 1.56, it is respectfully requested that this Supplemental Information Disclosure Statement be entered and the documents listed on attached Form PTO/SB/08 be considered by the Examiner and made of record. Copies of the listed documents are enclosed pursuant to 37 C.F.R. § 1.98(a).

In accordance with 37 C.F.R. § 1.97(g) and (h), filing of this Supplemental Information Disclosure Statement is not to be construed as a representation that a search has been made or an

admission that the information cited herein is, or is considered to be, material to patentability as defined in 37 C.F.R. § 1.56(b). Further, no representation is made by Applicant herein that no other possible material information as defined in 37 C.F.R. § 1.56(b) exists.

DOCUMENTS

Other Documents

Lee, H., et al., "An Optimized Densification of the Filled Oxide for Quarter Micron Shallow Trench Isolation (STI)," IEEE Symposium on VLSI Technology 1996, pp. 158-159.

Applicant offers to supply any explanation or discussion of the documents that the Examiner feels is necessary or desirable and which is requested.

This Supplemental Information Disclosure Statement is filed within three (3) months of the filing date of the above-identified application, and no certification pursuant to 37 C.F.R. § 1.97(c) or a fee pursuant to 37 C.F.R. § 1.17(p) is required.

Respectfully submitted,



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Date: November 11, 2002  
BGP/jml

Enclosures: Form PTO/SB/08  
Cited Document

Document in ProLaw

**Burden Hour Statement:** This form is estimated to take 2.0 hours to complete. Time will vary depending upon the needs of the individual case. Any comments on the amount of time you are required to complete this form should be sent to the Chief Information Officer, U.S. Patent and Trademark Office, Washington, DC 20231. DO NOT SEND FEES OR COMPLETED FORMS TO THIS ADDRESS. SEND TO: Commissioner for Patents, Washington, DC 20231.